

# Preliminary results from UFSD beam test @ FNAL

## Large collaboration, CMS – ATLAS groups involved

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# Key improvements of FNAL Beam test

Many groups involved → strong analyses community

Temperature control

Three read-out boards

Accurate tracking

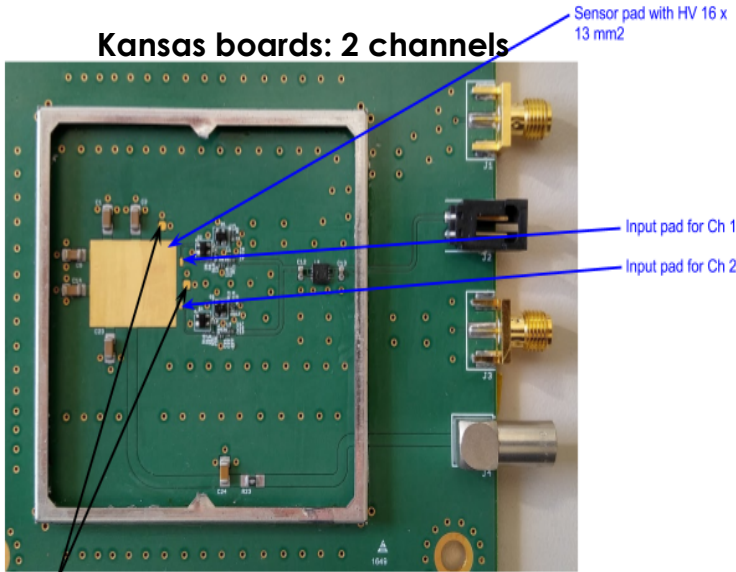
## **Results in this talk:**

- Time resolution
- Effect of temperature
- Efficiency scans vs x- and y-position
- Fill factor
- Effect of Al. metal cover on the UFSD response

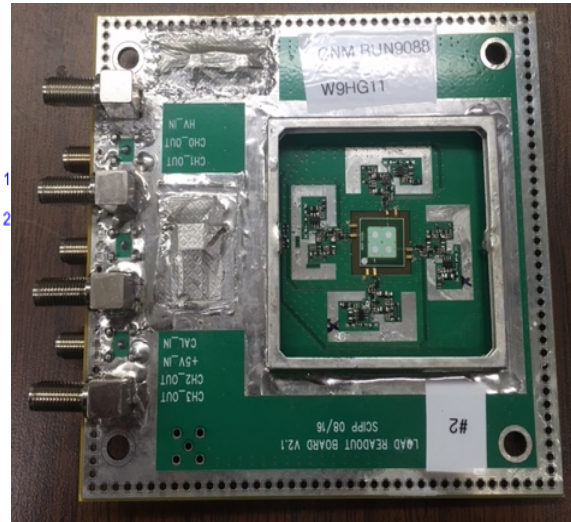
# The electronics: KU, UCSC, FNAL boards

Several boards with 2, 4 or 8 channels were used for the characterization of the UFSDs.

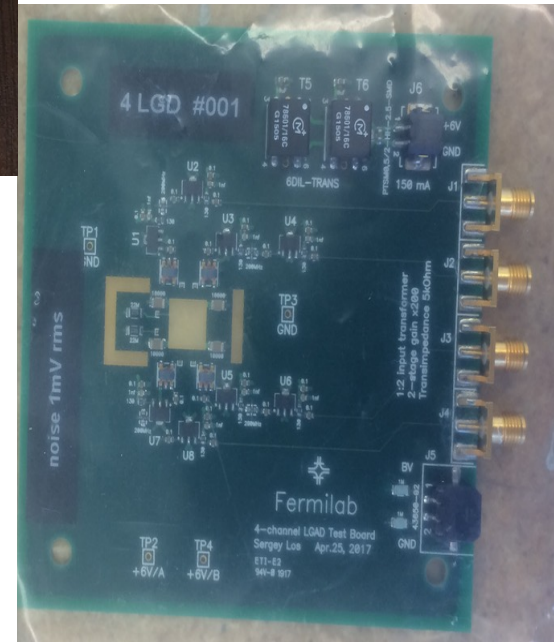
**Kansas boards: 2 channels**



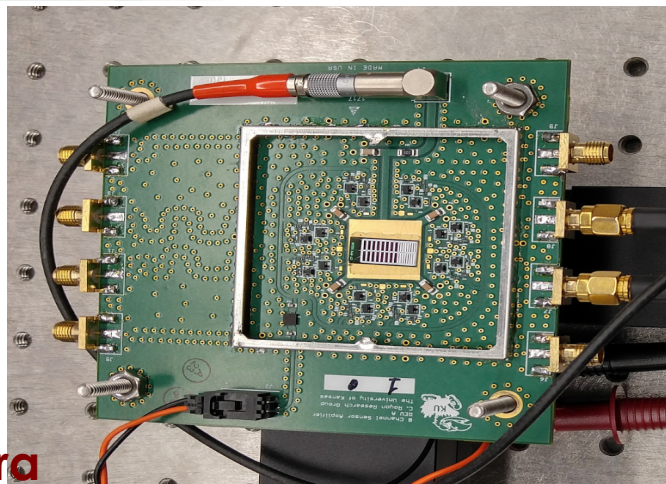
**UCSC boards: 4 channels**



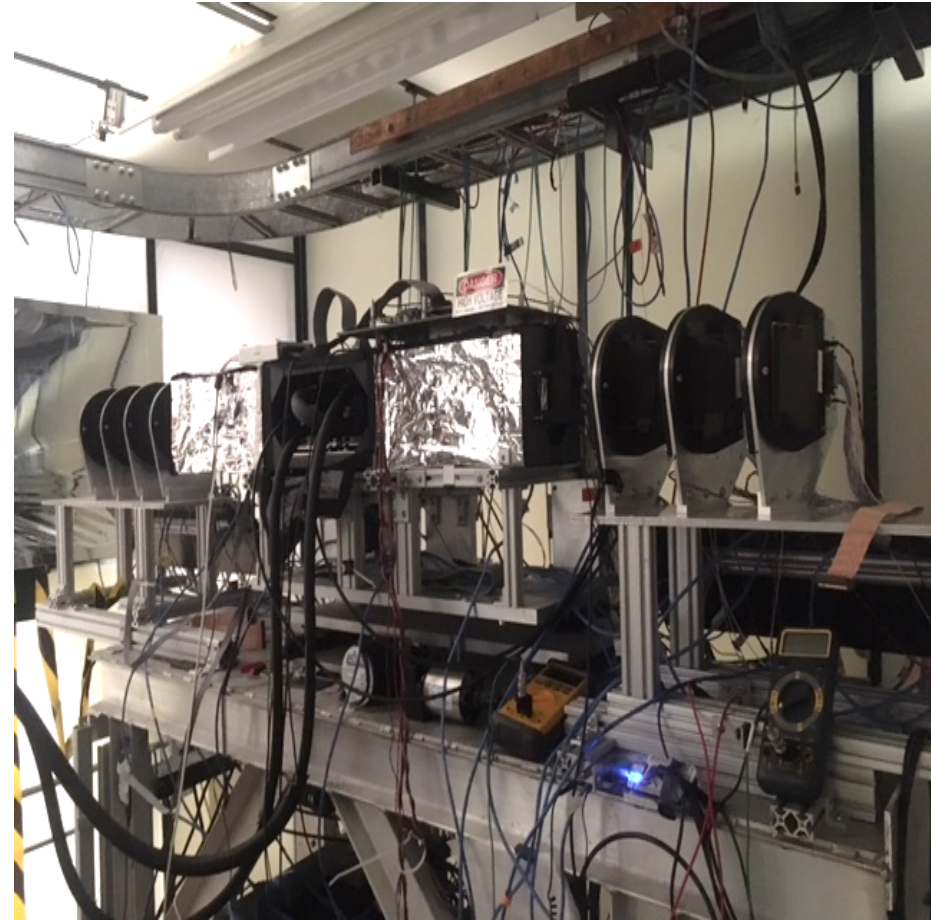
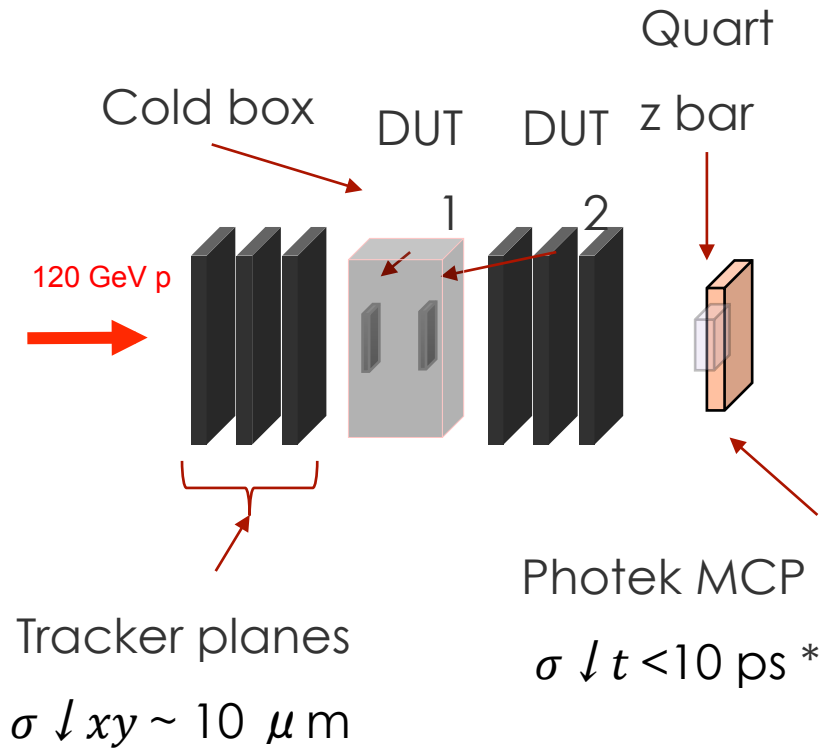
**FNAL boards: 4 channels**



**Kansas boards:  
8 channels**



# Fermilab Testbeam Facility



Chiller runs to -25C, a Peltier cell keeps stable the temperature of the boards at **-20C**  
Nitrogen gas keeps humidity low and prevent condensation

\* [Study of the timing performance of micro-channel plate photomultiplier for use as an active layer in a shower maximum detector, NIMA](#)

# Sensor and amplifier tested

The different sensors were tested using the different boards in various conditions: bias, temperature and irradiation

Sensor	KU board 2 ch	UCSC board 4 ch	FNAL board 4 ch
HPK 50A	-630V		
HPK 50B	-450V -550V -600V -510V -510V -570V		
HPK 50C	-400V	-410V -470V	
HPK 50D	-100V -200V -250V -300V -325V		-250V -300V -210V -250V -250V -280V
CNM W9HG11		-140V -160V	
HPK 50D 6e14 neq/cm <sup>2</sup>		-600V -635V	
CNM W11LGA35 6e14 neq/cm <sup>2</sup>			-400V -420V

Temperature:

20C

-10C

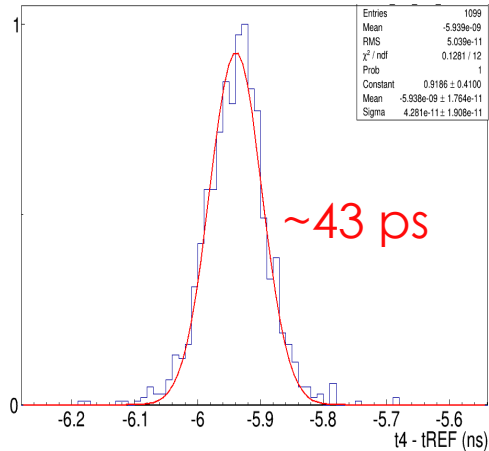
-20C



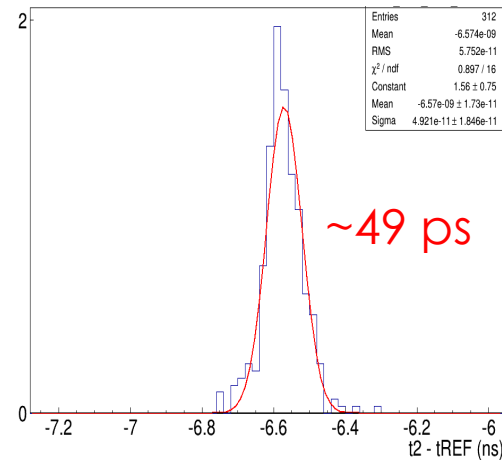
# Boards performance

All the tested amplifiers able to exploit the performance of the sensors

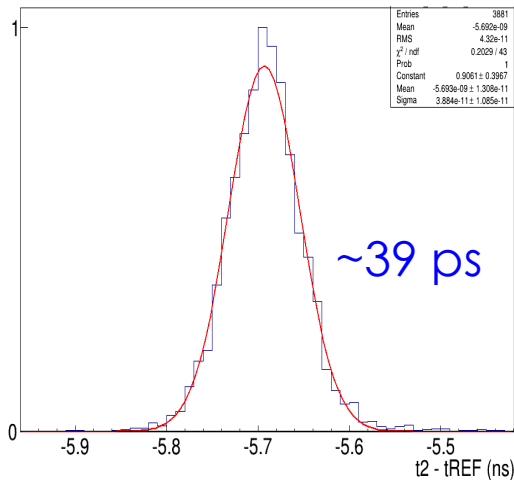
50C @ -400V on KU



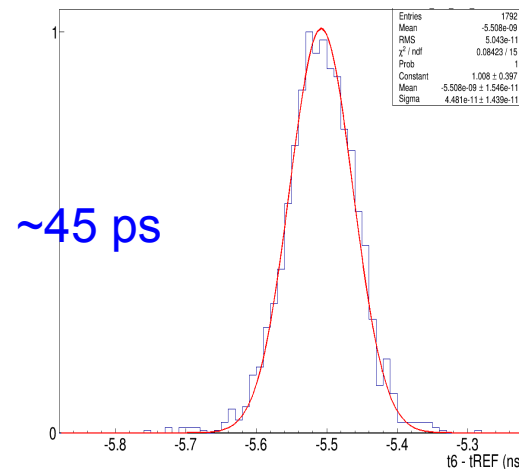
50C @ -410V on UCSC



50D @ -300V on KU



50D @ -300V on FNAL



LGAD R&D group  
BT FNAL May 2017, Preliminary

# Temperature dependence

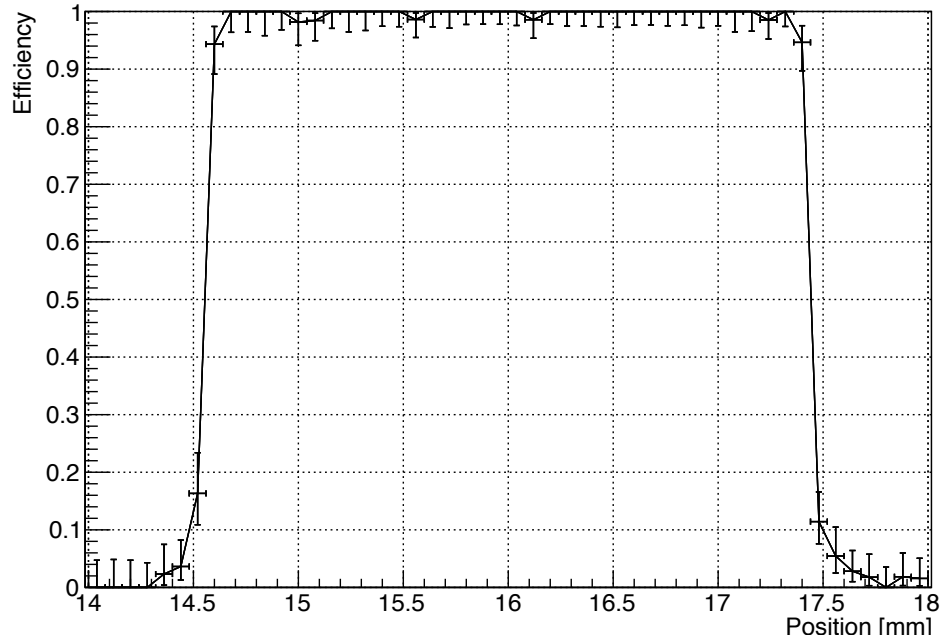
The gain of the sensor increases at lower temperatures while the effect on the noise is negligible: performances improve at low temperature

<b>HPK 50D on FNAL board -250V</b>	<b>MIP 20C (mV)</b>	<b>MIP -20C (mV)</b>	<b>noise 20C (mV)</b>	<b>noise -20C (mV)</b>	<b>SNR 20C</b>	<b>SNR -20C</b>
Ch 1	20	45	1.2	1.2	17	38
Ch 2	20	44	1.2	1.2	17	37
Ch 3	20	44	1.2	1.2	17	37
Ch 4	19	44	1.2	1.2	16	37

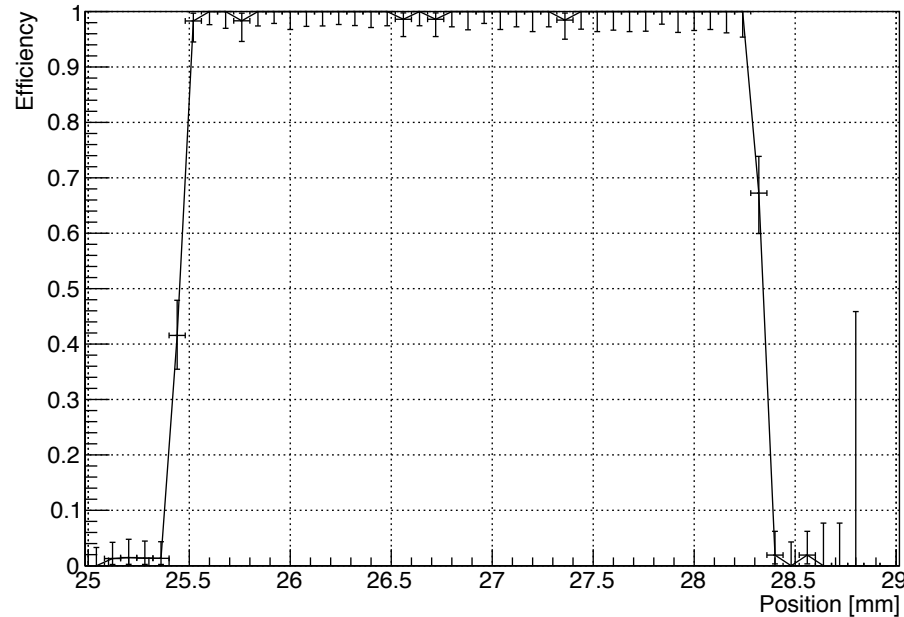
<b>HPK 50D on FNAL board @ -250V</b>	<b>Time precision (ps)</b>	<b>Time precision (ps)</b>
Ch 1	64	44
Ch 2	62	44
Ch 3	65	43
Ch 4	67	42

# HPK 50D Efficiency vs position

Very good tracking  
**100% efficiency**



**x-scan**



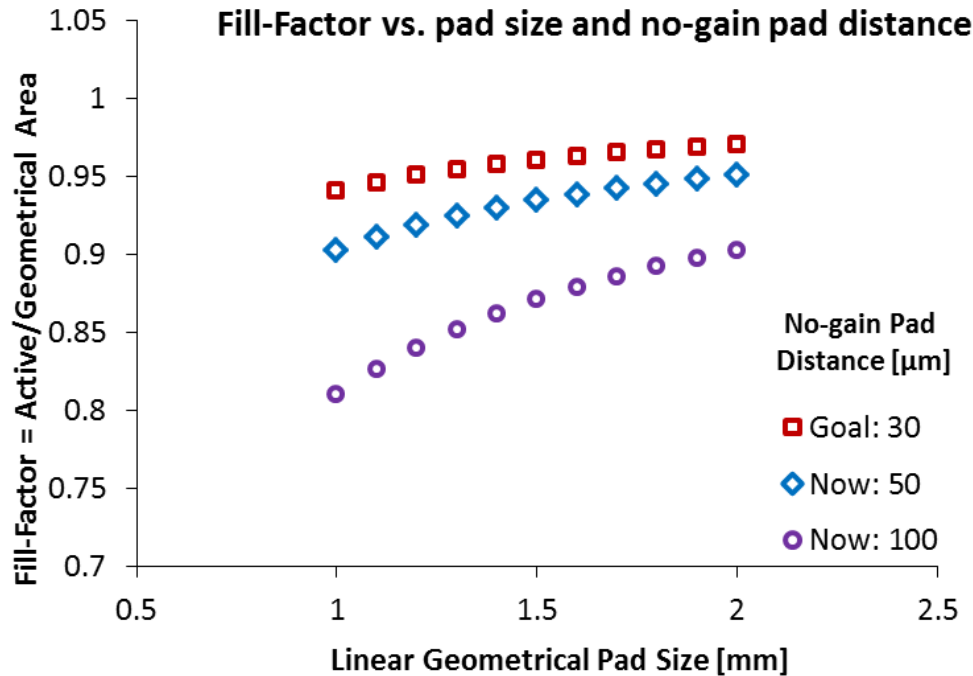
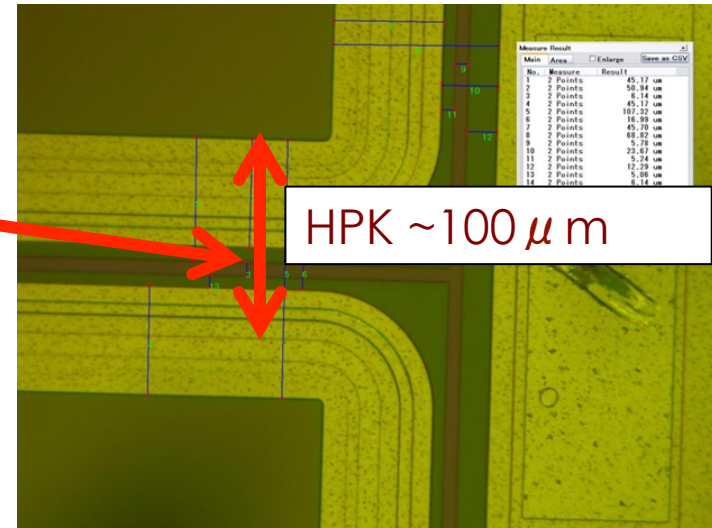
**y-scan**



# Fill-Factor vs. "no-gain" Pad Distance & Pad Size

Fill factor = Active Area / Geometrical Area

"no-gain" region between pads



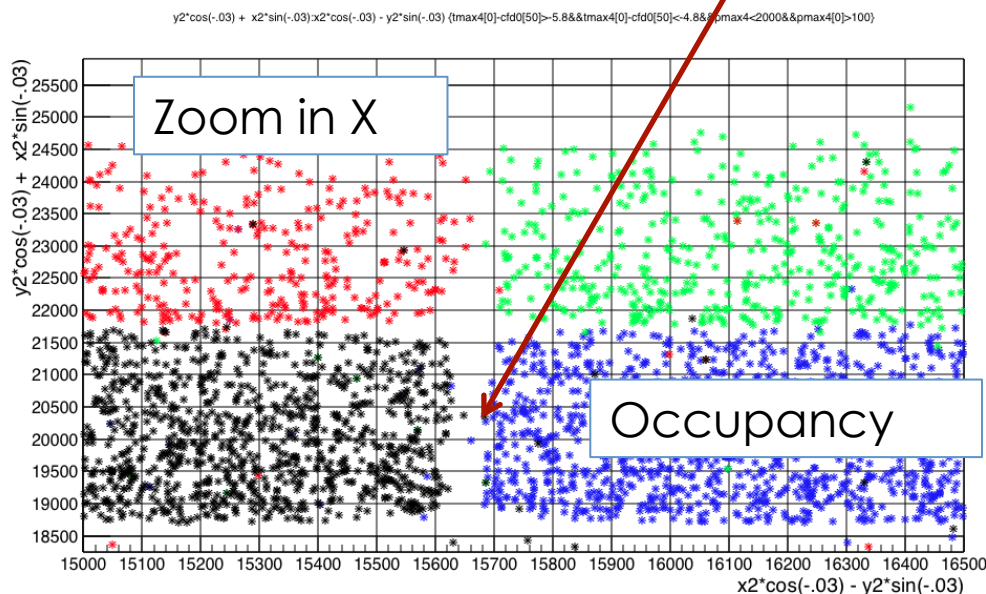
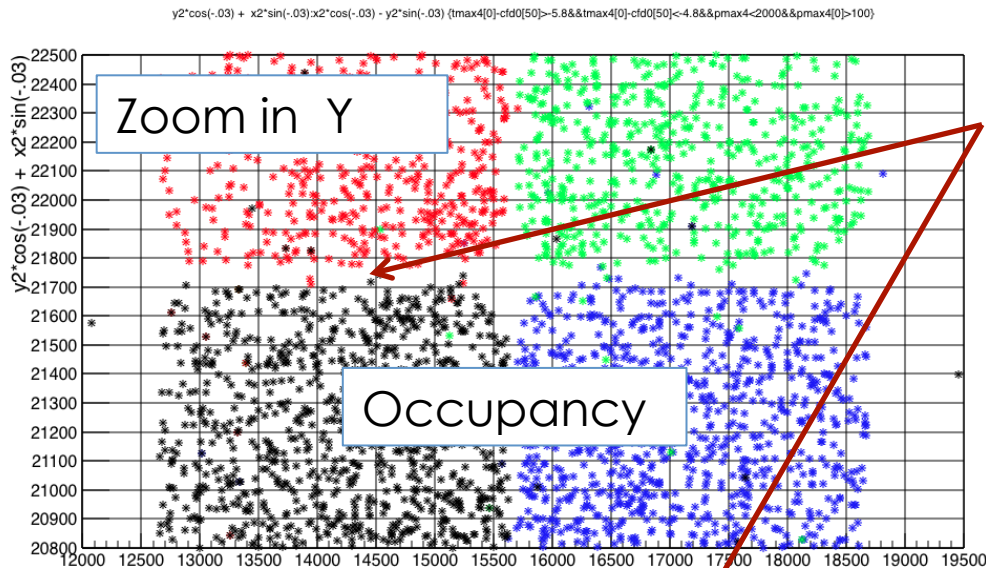
Is there a difference between CNM and HPK LGAD arrays?

At first look: no.

Both have 100 μm no-gain zone.  
Need to improve!

Improvement of fill factor with reduction of no-gain distance from 100 to 50 to 30 μm :  
Pad size 1mm: FF = 81% -> 90% -> 94%  
Pad size 1.4mm: FF = 86% -> 93% -> 96%

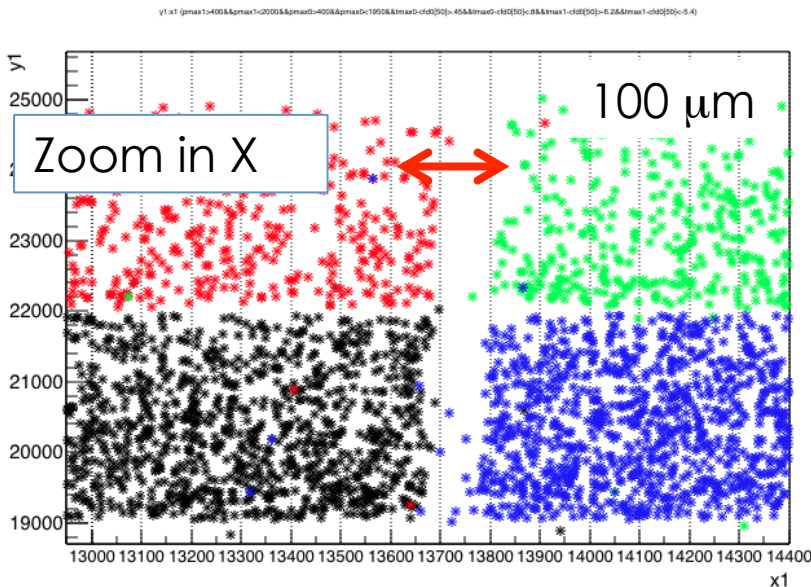
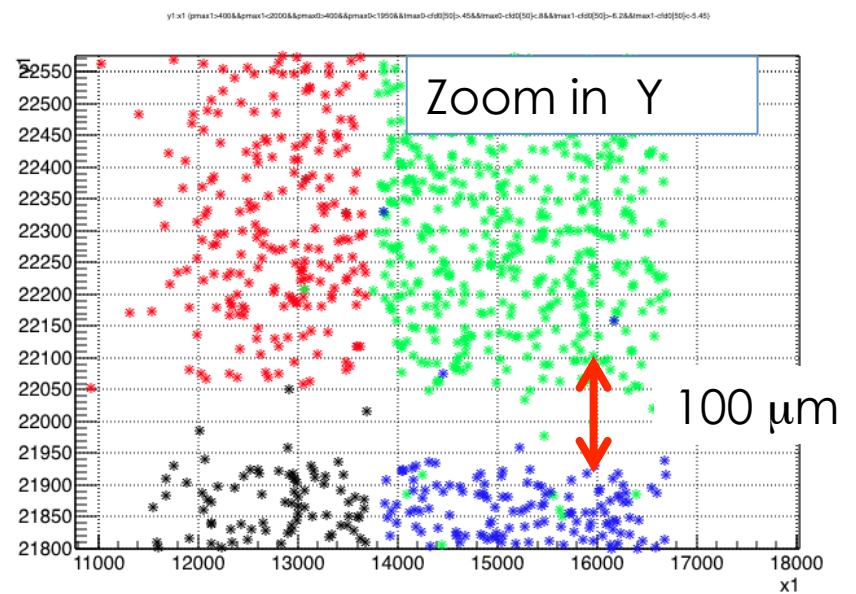
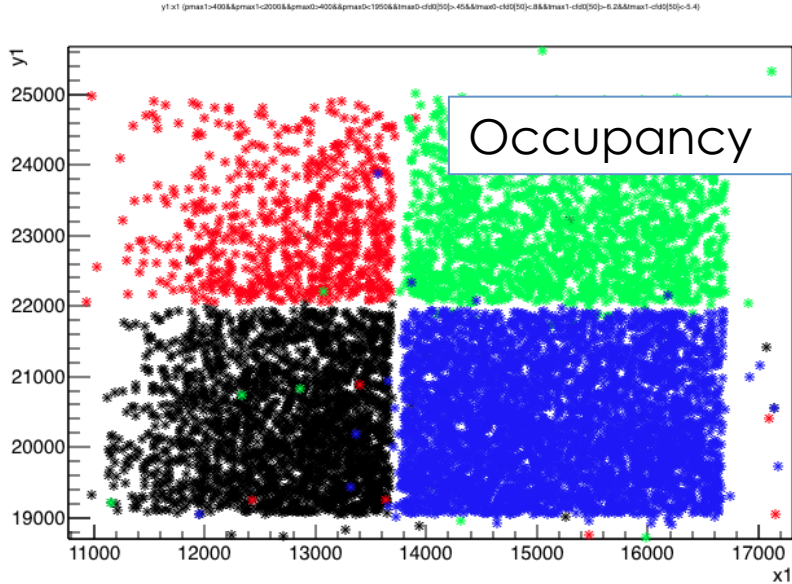
# CNM W9HG11 – Dead Area between 3x3 mm<sup>2</sup> pads



- Dead area is approximately 100  $\mu\text{m}$
- Approximately equal in horizontal and vertical directions
- Statistics may be too low for study of edge effects, for example amplitude as function of position

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# HPK 50C PIX – Dead Area between 3x3 mm<sup>2</sup> pads



The dead area has a width of  $\sim 100\mu\text{m}$ .

More refined analysis underway.

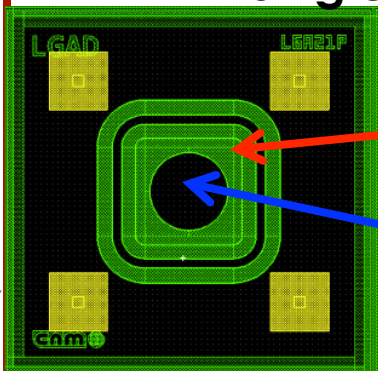
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Slide: H. Sadrozinski



# Effect of metal covering on the LGAD response

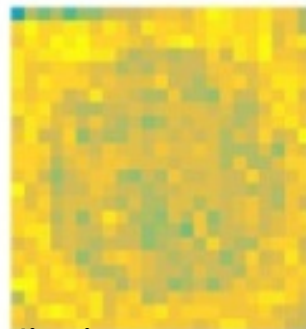
1 mm Single pad:



covered with Al

no Al

LGA31



Preliminary

Pre-rad

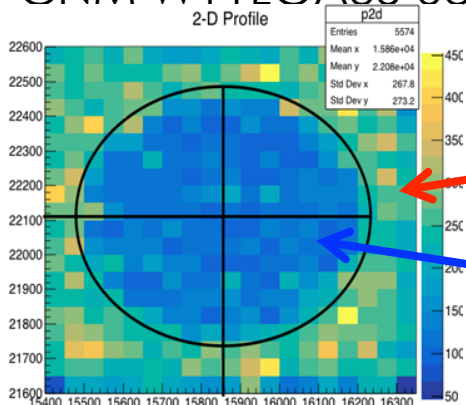
HGTD Beam Test:

(I. Nikolic and S. Trincaz-Duvold, LPNHE),  
CNM W5LGA31, +20C  
gain map shows ~10%  
effect

Post-rad

UCSC  $\beta$ -source & LGAD R&D beam test  
@ FNAL:

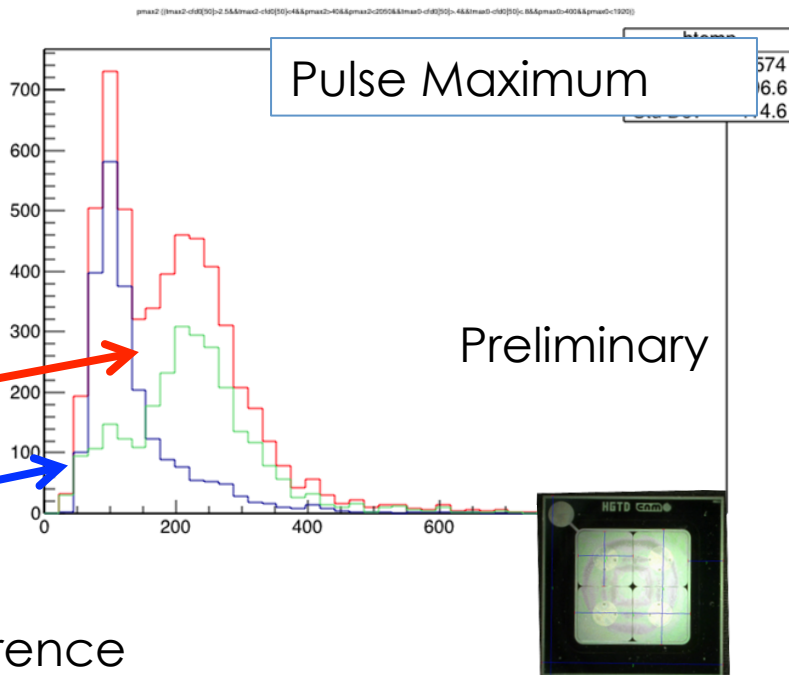
CNM W11LGA35  $6e14$  n/cm<sup>2</sup> -20C



covered with Al: 38ps

No Al: 44ps

Pulse maximum map  
shows a factor 2.5 difference



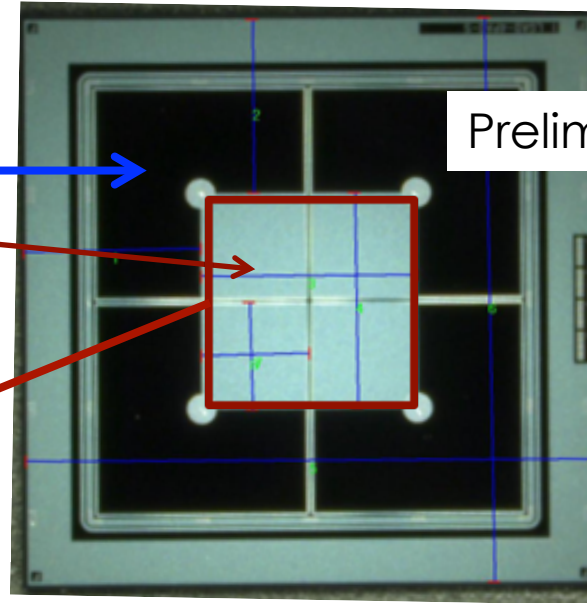
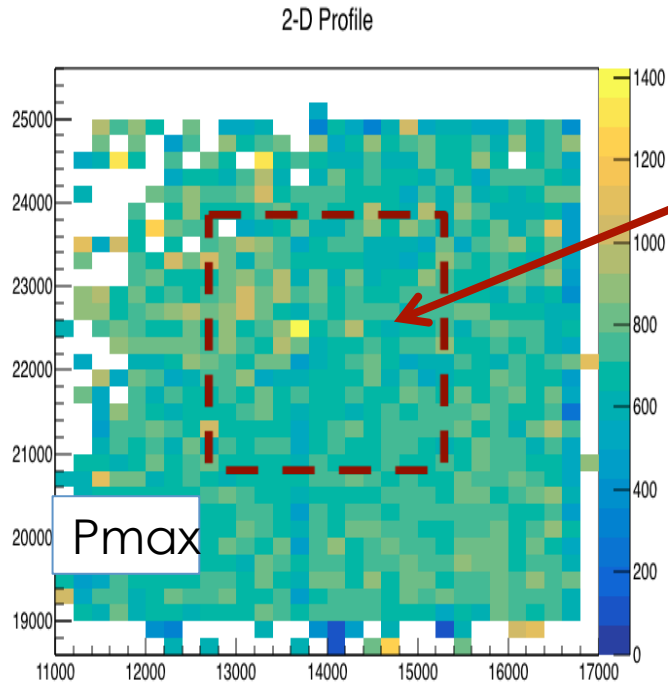
Preliminary

2x2 CNM Array (completely covered in metal) no effect pre-rad  
Preliminary

Slide: H. Sadrozinski

# Al metallization in HPK LGAD

2x2 3mm Array: large areas  
with / without metal covering



Pre-rad:  
**LGAD R&D beam test @ FNAL:**  
HPK 50C-PIX  
no difference between  
areas with and without metal covering.

Looking forward to a beam test campaign with irradiated HPK arrays and CNM single pads.

# Summary

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Very good collaboration from different groups and experiments

- Accurate tracking allows extracting a wealth of new information
- Time resolution of  $\sim 35 - 40$  ps confirmed by a lot of new results
- Strong effect of Temperature (for once an effect is actually helping)
- Good signal uniformity across pads
- Study of fill factor defines new R&D direction aimed at large area construction
- Need to understand AI-related difference in UFSD response. Is this a “universal effect” or it is a production effect?